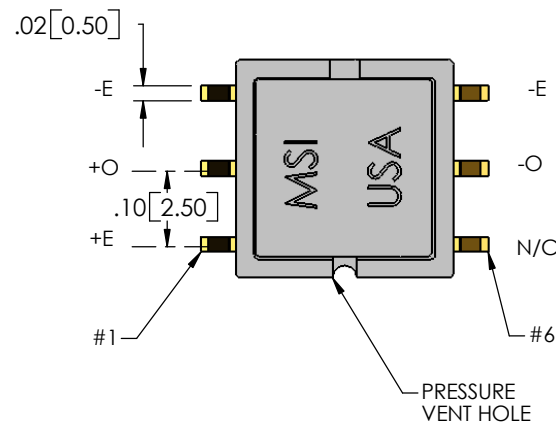


FIGURE # 1



PARAMETERS	MIN	TYP	MAX	UNITS	NOTES
PRESSURE		300		mmHg	
OUTPUT SPAN	21	43.5	66	mV	1
ZERO PRESSURE OUTPUT	-15		15	mV	1
PRESSURE NON-LINEARITY		$\pm 0.3$		%FS	1
PRESSURE HYSTERESIS		$\pm 0.7$		%FS	1
INPUT IMPEDANCE	2700	3300	3900	Ohm	
OUTPUT IMPEDANCE				Ohm	
TEMPERATURE ERROR-SPAN (5 to 45C)	-1.3		1.3	%FS	2
TEMPERATURE ERROR-ZERO (5 to 45C)	-10		10	%FS	2
SUPPLY CURRENT		1.5	3	mA	
OPERATING TEMPERATURE	-5		50	C	3
STORAGE TEMPERATURE	-20		70	C	
OVER PRESSURE			2X		
SOLDERING TEMPERATURE (SOLD.IRON)			300	C	7
HUMIDITY (NON CONDENSING)	25		85	%RH	9

- 1 REFERENCE CONDITIONS: TEMP 25C, 1.5mA SUPPLY
- 2 TEMP RANGE 5C TO 45C WITH RESPECT TO 25C
- 3 MAX OVERPRESSURE 2X RATED PRESSURE.
- 4 PRESSURE CONNECTION:
  - a) TUBING
- 5 MEDIA COMPATIBILITY:
  - a) NON-CORROSIVE GASES.
- 6 MOUNTING:
  - a) THIS PRODUCT IS DESIGNED TO BE MOUNTED ON A PCB IN HOLE'S DIA .035 in (0.9mm). SEE FIG. # 1 HOWEVER, EXCESSIVE BENDING OF LEADS WOULD RESULT IN SENSOR OUTPUT.
  - b) AFTER MOUNTING, PRECAUTION MUST BE TAKEN DURING TUBE INSTALLATION. EXCESSIVE FORCE MIGHT BEND THE PINS.
- 7 SOLDERING:
  - a) HAND SOLDERING, SOLDER IRON TEMP:260C TO 300C FOR 5 sec MAX
  - b) WAVE SOLDERING @ 240C PICK TEMP. FOR 5 sec. (PLUG PRESSURE PORTS BEFORE SOLDERING INSURING THAT FLUX FUMES ARE NOT TRAPPED INSIDE THE SENSOR.
  - c) NO CLEAN SOLDER IS RECOMMENDED.
- 8 CLEANING:
  - a) NO CLEANING SOLUTIONS ARE ALLOWED INSIDE PLASTIC LIDS.
  - b) NO CLEANING WITH WATER OR ULTRASONIC CLEANING.
- 9 DROP OF GEL IS ADDED ON THE DIE FOR MILD HUMIDITY APPLICATIONS.
- 10 APPLICATIONS: HEMODYNAMETER, GAS LEAK DETECTOR, VACUUM CLEANER, etc.
- 11 MODEL CODE: 1510-XY
  - X-OPTIONS:
    - #1 - LEAD PINS ARE OPPOSITE PRESSURE INLET DIRECTION
    - #2- LEAD PINS ARE SAME AS PRESSURE INLET DIRECTION
  - Y-OPTIONS:
    - N- NO GEL PROTECTION ON THE DIE.
    - F- GEL FILL PROTECTION ON THE DIE.